

IN THE CLAIMS:

Please AMEND claims 40, 42 and 43, as follows. For the Examiner's convenience, all claims currently pending in this application have been reproduced below:

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1-39. (Canceled)

40. (Currently Amended) A method of cutting an insulating substrate on which two-dimensionally arranged thin film semiconductor elements are installed, said method comprising the steps of:

cutting at least a slice line provided on the insulating substrate while detecting a misalignment of a cutting position from the slice line and correcting a the cutting position;

cutting the insulating substrate on a side opposing the slice line without correcting a cutting position on the side opposing the slice line; and

electrically ~~checking~~ confirming, after the cutting step is completed, whether a monitor line, ~~comprising an electrical conductor and~~ provided on a side where the thin film semiconductor elements are installed, is open.

41. (Previously Presented) The method according to claim 40, wherein the substrate is fixed on a stage having a groove corresponding to the slice line to cut the substrate.

42. (Currently Amended) The method according to claim 40, further comprising providing a guide line on the substrate and correcting the cutting position using the ~~guideline~~ guide line.

43. (Currently Amended) The method according to claim 40, wherein the slice line ~~comprises~~ is formed by an electrode layer simultaneously formed in parallel with an electrode layer constituting the thin film semiconductor element.

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